



Material Content Data Sheet



Sales Product Name	SGB30N60			Issued		29. August 2013		
MA#	MA000600086							
Package	PG-TO263-3-2			Weight*		1464.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.987	0.41	0.41	4087	4087
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		582	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175	
	non noble metal	copper	7440-50-8	851.691	58.14	58.22	581460	582217
wire	non noble metal	aluminium	7429-90-5	3.000	0.20	0.20	2048	2048
encapsulation	organic material	carbon black	1333-86-4	8.818	0.60		6020	
	plastics	epoxy resin	-	97.001	6.62		66224	
	inorganic material	silicondioxide	60676-86-0	482.065	32.91	40.13	329112	401356
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6593	6593
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	noble metal	silver	7440-22-4	0.130	0.01		89	
	non noble metal	tin	7440-31-5	0.104	0.01		71	
	non noble metal	lead	7439-92-1	4.955	0.34	0.36	3383	3543
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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